

IN THE SPECIFICATION

Please replace the paragraph beginning on page 2, line 17, with the following rewritten paragraph:

a1
FIG. 4a 4A is illustrates a wafer defect map and a scanning electron microscope according to the prior art. The wafer defect map 10 of FIG. 4a 4A was obtained using the KLA SEM 15, graphically represented by a rectangular box. FIG. 4b 4B is a bar graph of defects classified by type according to the prior art. The data in FIG. 4b 4B was analyzed in a conventional instrument having a review station using the defect map of FIG. 4a 4A.

Please insert the following new paragraph into the specification after the paragraph that begins on page 6, line 2.

a2
Mark 100a and mark 100b are just two possible detailed examples of markings 100 that could be used to identify types of defects in the wafer map 10a. Mark 100a is a dot mark, while mark 100b is a triangular mark. The vertical cross-hatching of mark 100a and the horizontal cross-hatching of mark 100b indicate that the two marks have different colors.